

Applicant

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

: Paul A. Farrar) Group Art Unit 2815

Appl. No. : 09/909,181

Filed : July 19, 2001

For : A METHOD OF USING

FOAMED INSULATORS IN

THREE DIMENSIONAL MULTICHIP STRUCTURES

Examiner : Chris C. Chu

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327,

October 7, 2002

Arlington, VA 22202, on

Minda H. Liu, Rev. No. 31,240

AMENDMENT

United States Patent and Trademark Office P.O. Box 2327 Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed July 5, 2002, please amend the above captioned application as follows:

IN THE DRAWINGS:

Please amend the drawings to conform to the drawings provided by the SUBMISSION OF PROPOSED DRAWING AMENDMENT FOR APPROVAL BY EXAMINER documented submitted concurrently herewith.

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A high density semiconductor structure having a plurality of integrated circuit chips, comprising:

a first integrated circuit chip having an upper bonding surface;